

9FW
PATENT



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants : Wilkins
Title : Die-First Multi-Chip Modules And Methods Of
Manufacture
Application No. : 10/724,981
Filed : November 30, 2003
Attorney Docket No. : 783403605015

I hereby certify that this correspondence
is being deposited today with the United
States Postal Service as first class mail in
an envelope addressed to: Commissioner for
Patents, P.O. Box 1450, Alexandria, VA
22313-1450

STATUS INQUIRY

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

on September 21, 2006
By: Kathie G. Kopeck

Dear Sir:

The above-referenced application was filed in the United States on
November 30, 2003, and we have not yet received an Office Action or Notice of
Allowance for the same. Please advise the undersigned when we should expect to
receive an action or notice.

Respectfully submitted,

David B. Cochran
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Date: 9/21/06